# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model:** HP chromebook 14a  
[List multiple models if applicable.]

**Product:** HP Chromebook 14a / B52 / 0GB  
**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm M/B, D/B</td>
<td>2</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td></td>
</tr>
</tbody>
</table>
| Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.) | Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”):  
  [ ] screws  
  [ ] snaps  
  [ ] adhesive  
  [ ] other. Explain ______  
  NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2. | 1                                     |
| Mercury-containing components                                                   | For example, mercury in lamps, display backlights, scanner lamps, switches, batteries |                                       |
| Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm            | Includes background illuminated displays with gas discharge lamps 14” | 1                                     |
| Cathode Ray Tubes (CRT)                                                        |                                                                      |                                       |
| Capacitors / condensers (Containing PCB/PCT)                                   |                                                                      |                                       |
| Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height |                                                                      |                                       |
| External electrical cables and cords                                            | DC Cable for External Power Supply                                   | 1                                     |
| Gas Discharge Lamps                                                             |                                                                      |                                       |
| Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs) |                                                                      |                                       |

**EL-MF877-00**  
**Template Revision C**  

Last revalidation date 09-May-2018

HPI instructions for this template are available at [EL-MF877-01](EL-MF877-01)
<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>(gel/paste) and toner</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw Driver</td>
<td>PH00 / PH0 / PH1</td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove Base rubber foot
2. Dis-fasten BASE Screw*8
3. Remove BASE and remove Battery connector
4. Dis-fasten Battery and speaker screw*8
5. Remove Battery and Speaker
6. Remove mylar and FFC
7. Dis-fasten DB Screw*4 and remove DB power cable connector
8. Remove DB
9. Remove MB connector (LVDS, KB, BL, TP, Antenna, camera) and remove power cable
10. Dis-fasten MB screw *8 and W-WAN Screw*1
11. Remove MB and remove W-WAN
12. Dis-fasten KB hook screw*2 and remove KB hook*2
13. Dis-fasten type-C BKT screw*2 and remove type-C BKT*2 (left and right)
14. Dis-fasten TP screw*6
15. Remove TP pad, TP-FFC and BKT
16. TOP remove release, dis-fasten Hinge screw *4
17. Remove LCD part
18. Remove Bezel,
19. Remove Panel Easy pull Adhesive and remove LCD cable connector and panel
20. Dis-fasten hinge bkt screw *6
21. Remove hinge*2 (left and right) and BKT

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HPI instructions for this template are available at EL-MF877-01
22. Remove antenna*2 (AUX and MAIN) and LCD cable
23. Remove camera module and camera cable connector
24. The END

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21
1. Remove Base rubber foot

![Base rubber foot removal](image1)

2. Dis-fasten BASE Screw*8

![Dis-fastening screws](image2)

3. Remove BASE and remove Battery connector

![BASE and Battery connector removal](image3)
4. Dis-fasten Battery and speaker screw*8

5. Remove Battery and Speaker

6. Remove mylar and FFC
7. Dis-fasten DB Screw*4 and remove DB power cable connector

8. Remove DB
9. Remove MB connector (LVDS, KB, BL, TP, Antenna, camera) and remove power cable

10. Dis-fasten MB screw*8 and W-WAN Screw*1

11. Remove MB and remove W-WAN

12. Dis-fasten KB hook screw*2 and remove KB hook*2

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13. Dis-fasten **type-C** BKT screw\(^2\) and remove **type-C** BKT\(^2\) (left and right)

14. Dis-fasten TP BKT screw\(^3\) and TP pad screw\(^3\)

15. Remove TP pad, TP-FFC and BKT

**HPI instructions for this template are available at EL-MF877-01**
16. TOP remove release, dis-fasten Hinge screw *4

17. Remove LCD part

18. Remove Bezel ,
19. Remove Panel Easy pull Adhesive and remove LCD cable connector and panel

20. Dis-fasten hinge bkt screw *6
21. Remove hinge*2 (left and right) and BKT

22. Remove antenna*2 (left and right) and lcd cable

23. Remove camera module and camera cable connector

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24. The END